

# EB2532YA12-12.000M TR

[Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Aug 17, 2020)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

Automotive Grade Quartz Crystal Resonator 2.5mm x 3.2mm x 0.8mm 4 Pad Ceramic Surface Mount (SMD)  
12.000MHz  $\pm 30$ ppm at 25°C,  $\pm 50$ ppm over -40°C to +125°C 12pF Parallel Resonant



## ELECTRICAL SPECIFICATIONS

Nominal Frequency	12.000MHz
Frequency Tolerance/Stability	$\pm 30$ ppm at 25°C, $\pm 50$ ppm over -40°C to +125°C
Aging at 25°C	$\pm 3$ ppm/Year Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance (C0)	3pF Maximum
Equivalent Series Resistance	100 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	200 $\mu$ Watts Maximum
Crystal Cut	AT-Cut
Spurious Response	-3dB Minimum (Measured from Fo to Fo +5000ppm)
Storage Temperature Range	-50°C to +150°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

## EB2532YA12-12.000M TR [Click part number to visit Part Number Details page](#)

### MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	No Connect

LINE	MARKING
1	
2	XXX XXX=Ecliptek Manufacturing Identifier

**Note:** Chamfer not shown.

**Seam Sealed**

**Terminal Plating Thickness:** Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

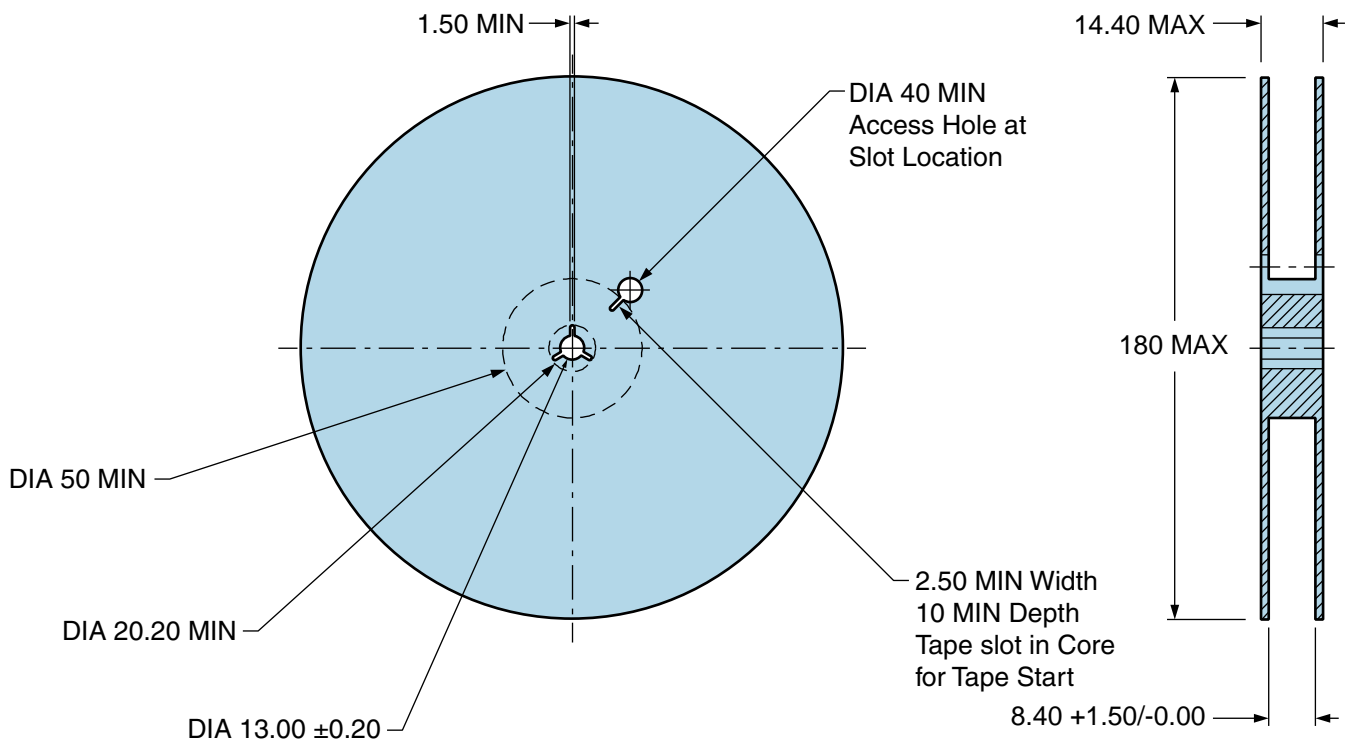
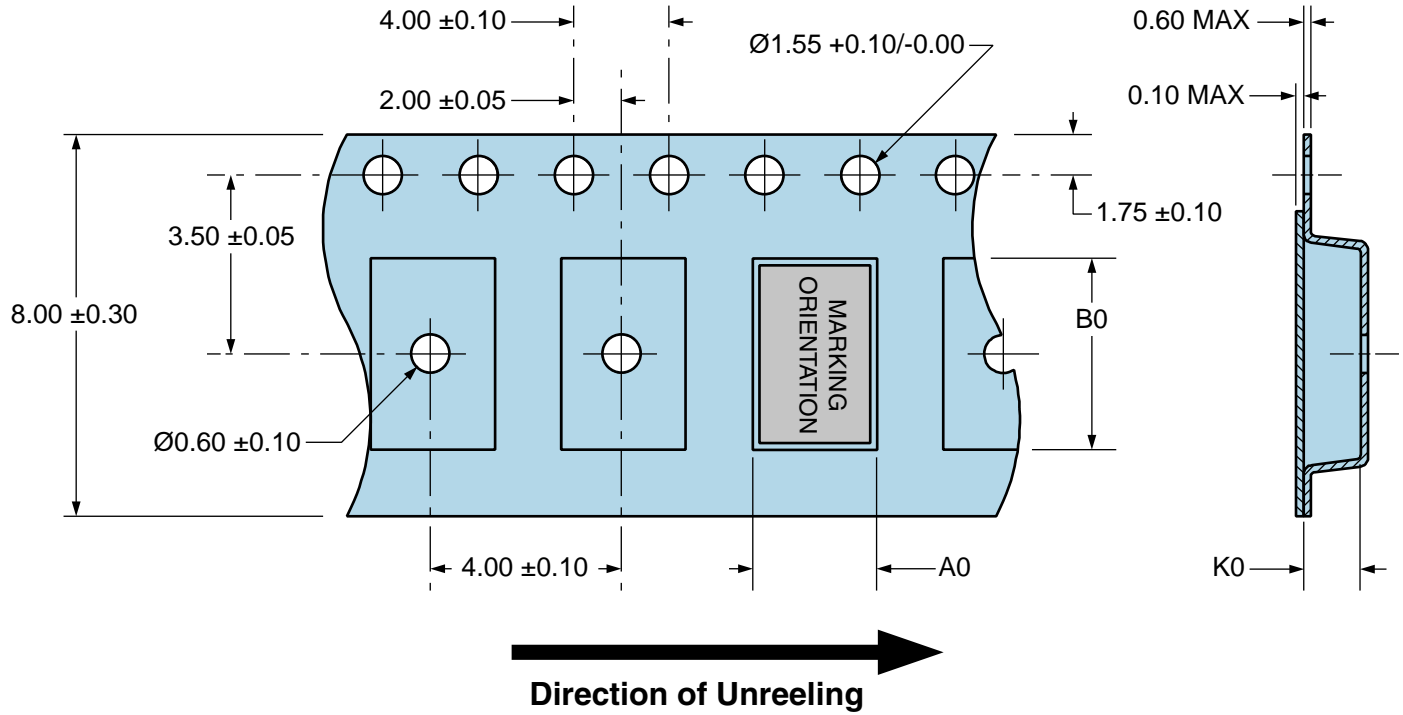
# EB2532YA12-12.000M TR

## Tape & Reel Dimensions

Quantity Per Reel: 3,000 units

All Dimensions in Millimeters

Compliant to EIA-481



# EB2532YA12-12.000M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

Ts MAX to Tl (Ramp-up Rate)	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
<b>Ramp-up Rate (Tl to Tp)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (Tl)	217°C
- Time (tL)	60 - 150 Seconds
<b>Peak Temperature (Tp)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (Tp Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (tp)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

# EB2532YA12-12.000M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

<b><math>T_S \text{ MAX}</math> to <math>T_L</math> (Ramp-up Rate)</b>	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S \text{ MIN}$ )	N/A
- Temperature Typical ( $T_S \text{ TYP}$ )	150°C
- Temperature Maximum ( $T_S \text{ MAX}$ )	N/A
- Time ( $t_s \text{ MIN}$ )	30 - 60 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	245°C Maximum
<b>Target Peak Temperature (<math>T_P \text{ Target}</math>)</b>	245°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [Crystals](#) category:*

*Click to view products by [Ecliptek / Abracon](#) manufacturer:*

Other Similar products are found below :

[CS325S24000000ABJT](#) [718-13.2-1](#) [MC405 32.0000K-R3:PURE SN](#) [FC-135R 32.7680KF-A3](#) [7A-40.000MAAE-T](#) [7B-27.000MBBK-T](#)  
[FL2000085](#) [9B-15.360MBBK-B](#) [9C-7.680MBBK-T](#) [ASH7K-32.768KHZ](#) [AT-41.600MAGQ-T](#) [BTD1062E05A-513](#) [LFXTAL066198Cutt](#)  
[9C-14.31818MBBK-T](#) [FC-12M 32.7680KA-AC3](#) [FC-12M 32.7680KA-X3](#) [SSPT7F-9PF20-R](#) [FX325BS-38.88EEM1201](#)  
[LFXTAL066431Cutt](#) [XT9S20ANA14M7456](#) [XT9SNLANA16M](#) [646G-24-2](#) [7A-24.576MBBK-T](#) [7B-30.000MBBK-T](#) [WX26-32.768K-6PF](#)  
[9B-14.31818MBBK-B](#) [CD1AM](#) [7B-25.000MAAE-T](#) [7A-14.31818MBBK-T](#) [6504-202-1501](#) [6526-202-1501](#) [FA-118T 27.1200MB50P-K0](#)  
[ABM12-104-37.400MHZT](#) [ABLS-10.000MHZ-D3W-T](#) [BTJ112E01E-513](#) [BTJ722K01C-7067](#) [BTL-20-513](#) [TSX-3225 24.0000MF15X-AC](#)  
[TSX-3225 16.0000MF18X-AC](#) [BTJ120E02C](#) [BTL-12-513](#) [7A-10.000MBBK-T](#) [7A-11.0592MBBK-T](#) [ABM12-103-24.000MHZT](#)  
[CS325S25000000ABJT](#) [ABM3B-25.000MHZ-B2-X-T](#) [FC-135 32.7680KA-A5](#) [FX0800015](#) [FP0800018](#) [3404](#)